



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD201-B2-03LRH E6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001309634						
<b>Package</b>		PG-TSLP-3-9		<b>Weight*</b>		0.50 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.07		698	
	noble metal	gold	7440-57-5	0.001	0.27		2705	
	inorganic material	silicon	7440-21-3	0.010	2.00	2.34	20050	23453
leadframe	non noble metal	nickel	7440-02-0	0.131	26.25	26.25	262523	262523
wire	noble metal	gold	7440-57-5	0.009	1.84	1.84	18361	18361
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.000	0.03		320	
	organic material	carbon black	1333-86-4	0.003	0.64		6398	
	plastics	epoxy resin	-	0.043	8.64		86369	
	inorganic material	silicondioxide	60676-86-0	0.273	54.67	63.98	546685	639772
leadfinish	noble metal	gold	7440-57-5	0.011	2.12	2.12	21228	21228
plating	noble metal	silver	7440-22-4	0.017	3.47	3.47	34663	34663
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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